

IN THE CLAIMS:

Please amend claims 32, 38, 41, 43, 51, 61, 65-66, and 68, without prejudice:

1. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one cleaning gas to the process chamber via a section connected to the process chamber; and

irradiating at least one light beam to the section or to the process chamber, wherein the light beam has an energy density ranging from about 1kW/mm² to about 2MW/mm² and assists dissociation of the cleaning gas in either the section or the process chamber, thereby achieving cleaning activity of the cleaning gas in the process chamber.

2. (Original) The method of claim 1, wherein the section is connected on top of the process chamber.

3. (Original) The method of claim 1, wherein the cleaning gas is selected from the group consisting of a fluorine-containing gas, a chlorine-containing gas and other halogen-containing gases.

4. (Previously presented) The method of claim 3, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

5. (Previously presented) The method of claim 1, wherein the light beam has a wavelength range from about 190 nm to about 10 μm.

6. (Cancelled)

7. (Previously presented) The method of claim 1, wherein the light beam comprises an incoherent light beam or a laser light beam.

8. (Previously presented) The method of claim 7, wherein the laser beam is focused or expanded.

9. (Previously presented) The method of claim 7, wherein the laser beam is a pulsed type or a continuous wave type laser beam(s).

10. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one halogen-containing cleaning gas to the process chamber via a section connected to the process chamber; and

irradiating at least one light beam comprising an incoherent light beam to the section or to the process chamber, wherein the light beam assists dissociation of the halogen-containing cleaning gas in either the section or the process chamber, thereby achieving cleaning activity of the halogen-containing cleaning gas in the process chamber.

11. (Original) The method of claim 10, wherein the section is connected on top of the process chamber.

12. (Original) The method of claim 10, wherein the halogen-containing gas is a fluorine-containing gas or a chlorine-containing gas.

13. (Previously presented) The method of claim 12, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

14. (Previously presented) The method of claim 10, wherein the light beam has a wavelength range from about 190 nm to about 10 μ m.

15. (Previously presented) The method of claim 10, wherein the light beam has an energy density range from about 1kW/mm² to about 2MW/mm².

16. (Previously presented) The method of claim 10, wherein the light beam is focused or expanded.

17. (Previously presented) The method of claim 10, wherein the light beam is a pulsed type or a continuous wave type laser beam.

18. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one fluorine-containing cleaning gas to the process chamber via a section connected to the process chamber; and

irradiating at least one laser beam having a wavelength range from about 190 nm to about 10 μ m and an energy density range from about 1 kW/mm² to about 2 MW/mm² to the section or to the process chamber,

wherein the laser beam assists dissociation of the fluorine-containing cleaning gas in either the section or the process chamber, thereby achieving cleaning activity of the fluorine-containing cleaning gas in the process chamber.

19. (Original) The method of claim 18, wherein the section is connected on top of the process chamber.

20. (Previously presented) The method of claim 18, wherein the fluorine containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

21. (Original) The method of claim 18, wherein the laser beam(s) is focused or expanded.

22. (Original) The method of claim 18, wherein the laser beam(s) is a pulsed type or a continuous wave type laser beam(s).

23. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one precursor gas to the process chamber via a section connected to the chamber;

applying at least one light beam to the section or directly to the process chamber, wherein the light beam has an energy density ranging from about 1kW/mm² to about 2MW/mm²; and

applying a plasma to the process chamber, wherein the plasma activates the precursor gas to generate reactive species, and wherein the light beam assists dissociation of the reactive species, thereby cleaning the process chamber.

24. (Original) The method of claim 23, wherein the reactive species are generated from a precursor gas selected from the group consisting of a fluorine-containing gas, a chlorine-containing gas, and other halogen-containing gases.

25. (Previously presented) The method of claim 24, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

26. (Previously presented) The method of claim 23, wherein the light beam has a wavelength range from about 190 nm to about 10 μ m.

27. (Cancelled)

28. (Previously presented) The method of claim 23, wherein the light beam comprises an incoherent light beam or a laser light beam.

29. (Previously presented) The method of claim 28, wherein the laser light beam is focused or expanded.

30. (Previously presented) The method of claim 28, wherein the laser light beam is a pulsed type or a continuous wave type.

31. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one halogen-containing precursor gas to the process chamber via a section connected to the process chamber;

applying at least one light beam comprising an incoherent light beam to the section or directly to the process chamber; and

applying a plasma to the process chamber, wherein the plasma activates the precursor gas to generate reactive species, and wherein the light beam assists dissociation of the reactive species, thereby cleaning the process chamber.

32. (Currently amended) The method of claim 31, wherein the reactive species is are generated from a fluorine-containing gas or a chlorine-containing gas.

33. (Previously presented) The method of claim 32, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

34. (Previously presented) The method of claim 31, wherein the light beam has a wavelength range from about 190 nm to about 10 μ m.

35. (Previously presented) The method of claim 31, wherein the light beam has an energy density range from about 1 W/mm² to about 2 MW/mm².

36. (Previously presented) The method of claim 31, wherein the light beam is focused or expanded.

37. (Previously presented) The method of claim 31, wherein the light beam is a pulsed type or a continuous wave type.

38. (Currently amended) A method for cleaning a process chamber, comprising the steps of:

introducing at least one fluorine-containing precursor gas to the process chamber via a section connected to the process chamber;

applying at least one laser beam having a wavelength range from about 190 nm to about 10 μ m and an energy density range from about 1 W/mm² KW/mm² to about 2 MW/mm² to the section or directly to the process chamber; and

applying a plasma to the process chamber, wherein the plasma activates the

fluorine-containing precursor gas to generate reactive species, and wherein the laser beam assists dissociation of the reactive species, thereby cleaning the process chamber.

39. (Previously presented) The method of claim 38, wherein the fluorine-containing precursor gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

40. (Previously presented) The method of claim 38, wherein the laser light beam is focused or expanded.

41. (Currently amended) The method of claim 30 38, wherein the laser light beam is a pulsed type or a continuous wave type.

42. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one precursor gas to a remote chamber, wherein the remote chamber is connected to the interior of the process chamber;

activating the precursor gas in the remote chamber to generate reactive species;

introducing the reactive species to the process chamber via a section connected to the chamber; and

applying at least one light beam to the section, wherein the light beam has an energy density range from about 1 kW/mm² to about 2 MW/mm² and assists dissociation of the reactive species, thereby cleaning the process chamber.

43. (Currently amended) The method of claim 42, wherein the reactive species is are generated from a precursor gas selected from the group consisting of a fluorine-

containing gas, a chlorine-containing gas and other halogen-containing gases.

44. (Previously presented) The method of claim 43, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

45. (Previously presented) The method of claim 42, wherein the light beam has a wavelength range from about 190 nm to about 10 μ m.

46. (Cancelled)

47. (Previously presented) The method of claim 42, wherein the light beam comprises an incoherent light beam or a laser light beam.

48. (Previously presented) The method of claim 47, wherein the laser light beam is focused or expanded.

49. (Previously presented) The method of claim 47, wherein the laser light beam is a pulsed type or a continuous wave type.

50. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one halogen-containing precursor gas to a remote chamber, wherein the remote chamber is connected to the interior of the process chamber;

activating the halogen-containing precursor gas in the remote chamber to generate reactive species;

introducing the reactive species to the process chamber via a section connected to the chamber; and

applying at least one light beam comprising an incoherent light beam to the section, wherein the light beam assists dissociation of the reactive species, thereby cleaning the process chamber.

51. (Currently amended) The method of claim 50, wherein the reactive species is generated from a fluorine-containing gas or a chlorine-containing gas.

52. (Previously presented) The method of claim 51, wherein the fluorine-containing gas is selected from the group consisting of F₂, NF₃, SF₆, C₂F₆, CF₄, C₃F₈, and HF.

53. (Previously presented) The method of claim 50, wherein the light beam has a wavelength range from about 190 nm to about 10 μ m.

54. (Previously presented) The method of claim 50, wherein the light beam has an energy density range from about 1 W/mm² to about 2 MW/mm².

55. (Previously presented) The method of claim 50, wherein the light beam is focused or expanded.

56. (Previously presented) The method of claim 50, wherein the light beam is a pulsed type or a continuous wave type.

57. (Previously presented) A method for cleaning a process chamber, comprising the steps of:

introducing at least one fluorine-containing precursor gas to a remote chamber, wherein the remote chamber is connected to the interior of the process chamber;

activating the fluorine-containing precursor gas in the remote chamber to generate reactive species;

introducing the reactive species to the process chamber via a section connected to the chamber; and

applying at least one laser beam having a wavelength range from about 190 nm to about 10 μ m and an energy density range from about 1 kW/mm² to about 2 MW/mm² to the section, wherein the laser beam assists dissociation of the reactive species, thereby cleaning the process chamber.

58. (Previously presented) The method of claim 57, wherein the fluorine-containing precursor gas is selected from the group consisting of F₂, NF₃, C₂F₆, CF₄, C₃F₈, and HF.

59. (Previously presented) The method of claim 57, wherein the laser light beam is focused or expanded.

60. (Previously presented) The method of claim 57, wherein the laser light beam is a pulsed type or a continuous wave type.

61. (Currently amended) A method for cleaning a process chamber, comprising the steps of:

irradiating at least one laser beam to the interior of the process chamber, wherein the laser beam ablates residues from the process chamber; and

removing the process residues from the process chamber by introducing at least one carrier gas, thereby cleaning the process chamber.

62. (Original) The method of claim 61, wherein the laser beam(s) is a pulsed type or a continuous wave type.

63. (Original) The method of claim 61, wherein the laser beam(s) has a wavelength range from about 190 nm to about 10 μ m.

64. (Original) The method of claim 61, wherein the laser beam(s) has an energy density range from about 1 kW/mm² to about 2 MW/mm².

65. (Currently amended) The method of claim 61, wherein the carrier gas is selected from the group consisting of HF, N₂, Ar, H₂, and He.

66. (Currently amended) A method for cleaning a process chamber, comprising the steps of:

irradiating at least one laser beam having a wavelength range from about 190 nm to about 10 μ m and an energy density range from about 1 W/mm² to about 2 MW/mm² to the interior of the process chamber, wherein the laser beam ablates residues from the process chamber; and

removing the process residues from the process chamber by introducing at least one carrier gas, thereby cleaning the process chamber.

67. (Original) The method of claim 66, wherein the laser beam(s) is a pulsed type or a continuous wave type.

68. (Currently amended) The method of claim 66, wherein the carrier gas is selected from the group consisting of HF, N₂, Ar, H₂, and He.